

**NPN medium power transistors****BSP41; BSP43****FEATURES**

- High current (max. 1 A)
- Low voltage (max. 80 V).

**APPLICATIONS**

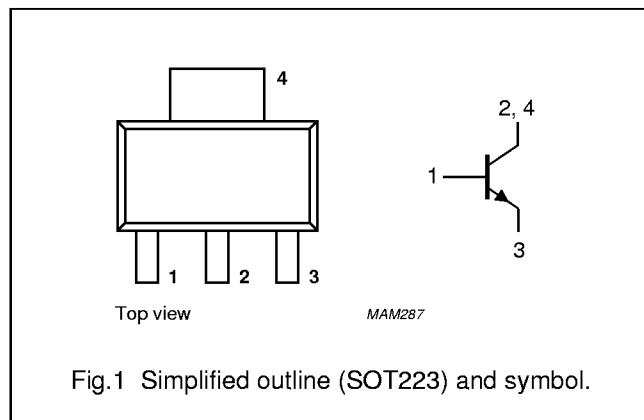
- Telephony and general industrial applications
- Thick and thin-film circuits.

**DESCRIPTION**

NPN medium power transistor in a SOT223 plastic package. PNP complements: BSP31; BSP32 and BSP33.

**PINNING**

PIN	DESCRIPTION
1	base
2,4	collector
3	emitter

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage BSP41 BSP43	open emitter	– –	70 90	V V
$V_{CEO}$	collector-emitter voltage BSP41 BSP43	open base	– –	60 80	V V
$V_{EBO}$	emitter-base voltage	open collector	–	5	V
$I_C$	collector current (DC)		–	1	A
$I_{CM}$	peak collector current		–	2	A
$I_{BM}$	peak base current		–	0.2	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25^\circ\text{C}$ ; note 1	–	1.3	W
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–	150	°C
$T_{amb}$	operating ambient temperature		–65	+150	°C

**Note**

1. Device mounted on a printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm<sup>2</sup>. For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

## NPN medium power transistors

BSP41; BSP43

**THERMAL CHARACTERISTICS**

<b>SYMBOL</b>	<b>PARAMETER</b>	<b>CONDITIONS</b>	<b>VALUE</b>	<b>UNIT</b>
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	93	K/W
$R_{th\ j-s}$	thermal resistance from junction to soldering point		12	K/W

**Note**

1. Device mounted on a printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm<sup>2</sup>.  
For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

**CHARACTERISTICS** $T_{amb} = 25^\circ C$  unless otherwise specified.

<b>SYMBOL</b>	<b>PARAMETER</b>	<b>CONDITIONS</b>	<b>MIN.</b>	<b>MAX.</b>	<b>UNIT</b>
$I_{CBO}$	collector cut-off current	$I_E = 0$ ; $V_{CB} = 60 V$	–	100	nA
		$I_E = 0$ ; $V_{CB} = 60 V$ ; $T_j = 150^\circ C$	–	50	$\mu A$
$I_{EBO}$	emitter cut-off current	$I_C = 0$ ; $V_{EB} = 5 V$	–	100	nA
$h_{FE}$	DC current gain	$I_C = 100 \mu A$ ; $V_{CE} = 5 V$ ; note 1	30	–	
		$I_C = 100 mA$ ; $V_{CE} = 5 V$ ; note 1	100	300	
		$I_C = 500 mA$ ; $V_{CE} = 5 V$ ; note 1	50	–	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 150 mA$ ; $I_B = 15 mA$ ; note 1	–	0.25	V
		$I_C = 500 mA$ ; $I_B = 50 mA$ ; note 1	–	0.5	V
$V_{BEsat}$	base-emitter saturation voltage	$I_C = 150 mA$ ; $I_B = 15 mA$ ; note 1	–	1	V
		$I_C = 500 mA$ ; $I_B = 50 mA$ ; note 1	–	1.2	V
$f_T$	transition frequency	$I_C = 50 mA$ ; $V_{CE} = 10 V$ ; $f = 100 MHz$	100	–	MHz

**Note**

1. Pulse test:  $t_p \leq 300 \mu s$ ;  $\delta \leq 0.01$ .

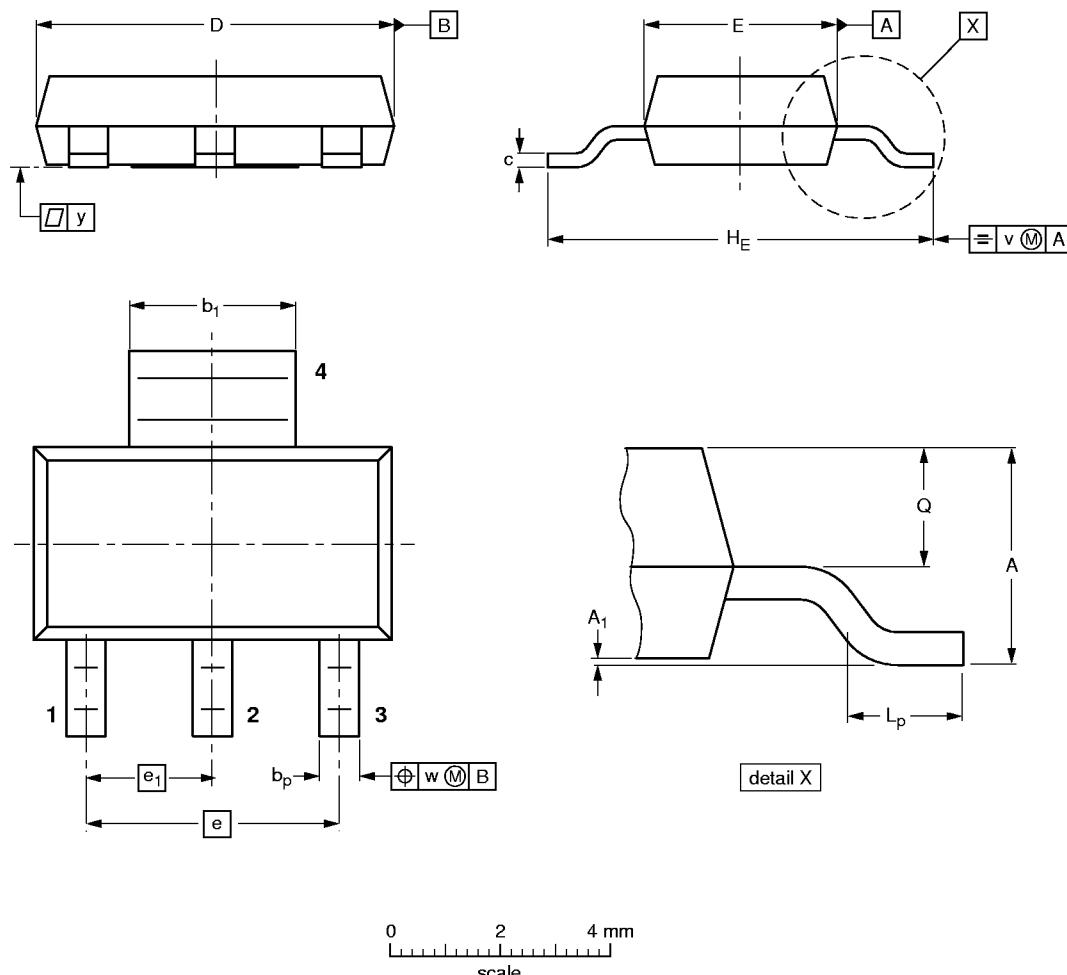
## NPN medium power transistors

BSP41; BSP43

## PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



## DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b <sub>p</sub>	b <sub>1</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w	y
mm	1.8	0.10	0.80	3.1	0.32	6.7	3.7	4.6	2.3	7.3	1.1	0.95	0.2	0.1	0.1
	1.5	0.01	0.60	2.9	0.22	6.3	3.3			6.7	0.7	0.85			

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT223						96-11-11 97-02-28